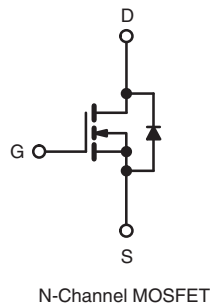
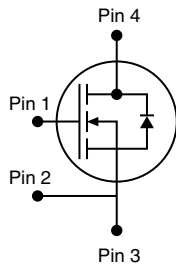
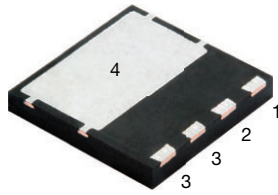


E Series Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V) at T_J max.	650	
$R_{DS(on)}$ typ. (Ω) at 25 °C	$V_{GS} = 10$ V	0.117
Q_g max. (nC)	116	
Q_{gs} (nC)	18	
Q_{gd} (nC)	33	
Configuration	Single	

PowerPAK® 8 x 8


FEATURES

- Fully lead (Pb)-free device
- Low figure-of-merit (FOM) $R_{on} \times Q_g$
- Low input capacitance (C_{iss})
- Reduced switching and conduction losses
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)
- Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and Halogen-free	SiHH26N60E-T1-GE3


ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V_{DS}	600	V	
Gate-Source Voltage	V_{GS}	± 30		
Continuous Drain Current ($T_J = 150$ °C)	V_{GS} at 10 V	$T_C = 25$ °C	25	A
		$T_C = 100$ °C	16	
Pulsed Drain Current ^a		I_{DM}	50	
Linear Derating Factor			1.6	W/°C
Single Pulse Avalanche Energy ^b		E_{AS}	353	mJ
Maximum Power Dissipation		P_D	202	W
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to +150	°C
Drain-Source Voltage Slope	$T_J = 125$ °C	dV/dt	37	V/ns
Reverse Diode dV/dt ^c			20	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 140$ V, starting $T_J = 25$ °C, $L = 28.2$ mH, $R_g = 25$ Ω , $I_{AS} = 5$ A.
- $I_{SD} \leq I_D$, $dI/dt = 100$ A/ μ s, starting $T_J = 25$ °C.



THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	38	50	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	0.48	0.62	

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		600	-	-	V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = 1 mA		-	0.67	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2	-	4	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
		V _{GS} = ± 30 V		-	-	± 1	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V		-	-	1	μA
		V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C		-	-	50	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 13 A	-	0.117	0.135	Ω
Forward Transconductance	g _{fs}	V _{DS} = 30 V, I _D = 13 A		-	8.6	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		-	2815	-	pF
Output Capacitance	C _{oss}			-	125	-	
Reverse Transfer Capacitance	C _{rss}			-	7	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}			-	124	-	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	381	-	
Total Gate Charge	Q _g	V _{GS} = 10 V	I _D = 13 A, V _{DS} = 480 V	-	77	116	nC
Gate-Source Charge	Q _{gs}			-	18	-	
Gate-Drain Charge	Q _{gd}			-	33	-	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 480 V, I _D = 13 A, V _{GS} = 10 V, R _g = 9.1 Ω		-	28	56	ns
Rise Time	t _r			-	54	81	
Turn-Off Delay Time	t _{d(off)}			-	80	120	
Fall Time	t _f			-	45	90	
Gate Input Resistance	R _g			f = 1 MHz, open drain		0.2	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	25	A
Pulsed Diode Forward Current	I _{SM}			-	-	50	
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 13 A, V _{GS} = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = I _S = 13 A, dI/dt = 100 A/μs, V _R = 25 V		-	459	918	ns
Reverse Recovery Charge	Q _{rr}			-	7.6	15.2	μC
Reverse Recovery Current	I _{RRM}			-	28	-	A

Notes

- a. C_{oss(er)} is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}.
- b. C_{oss(tr)} is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

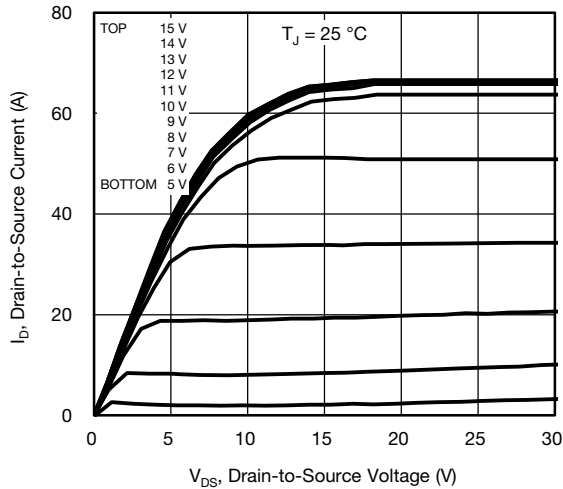


Fig. 1 - Typical Output Characteristics

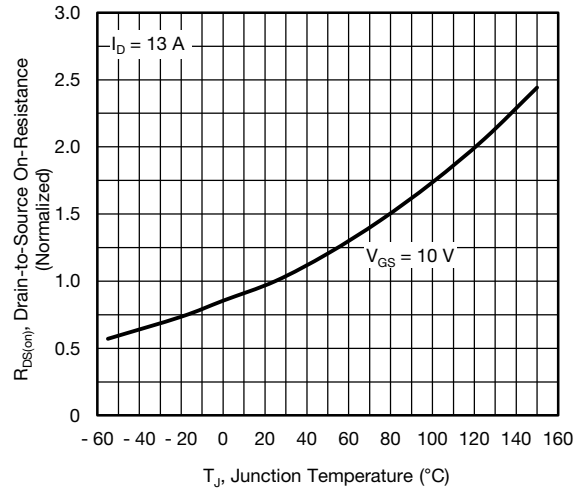


Fig. 4 - Normalized On-Resistance vs. Temperature

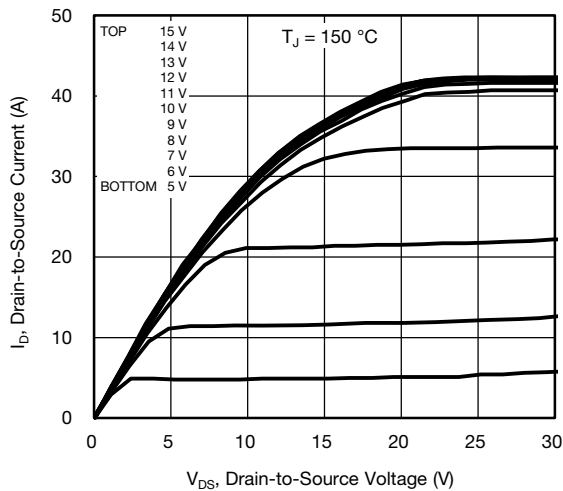


Fig. 2 - Typical Output Characteristics

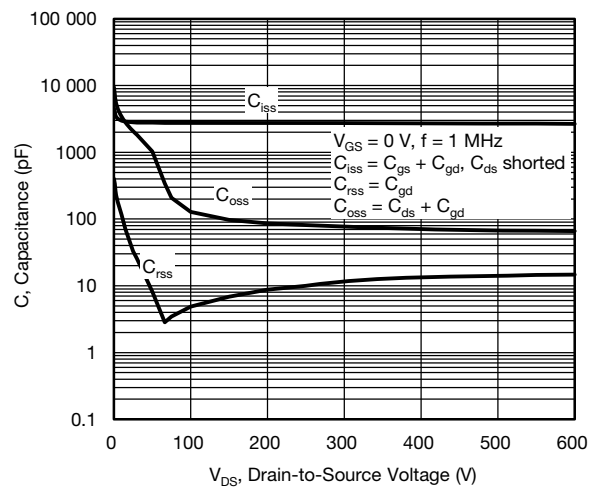


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

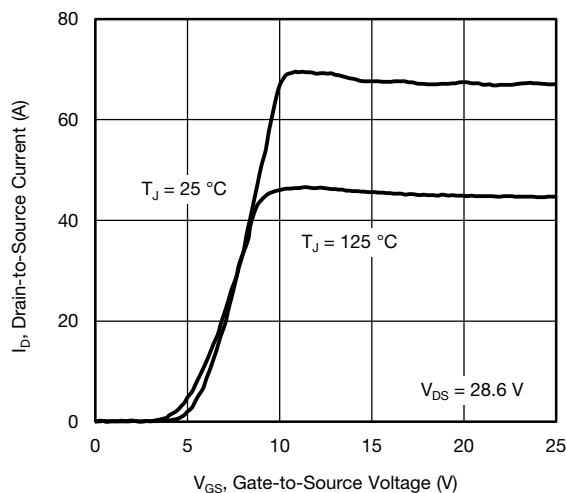


Fig. 3 - Typical Transfer Characteristics

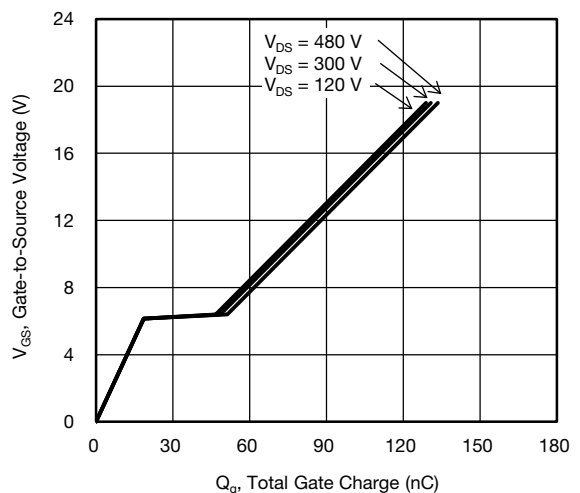


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

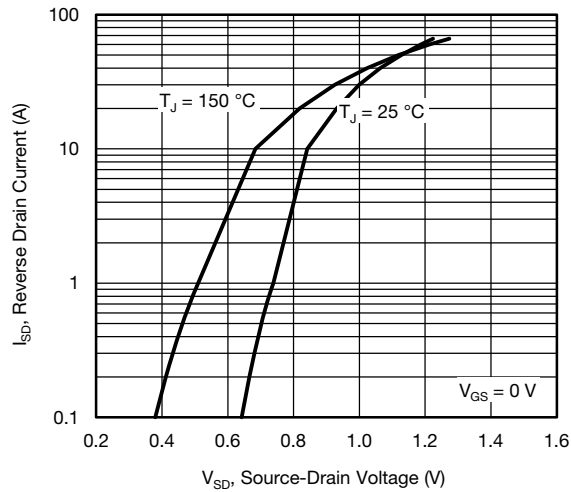


Fig. 7 - Typical Source-Drain Diode Forward Voltage

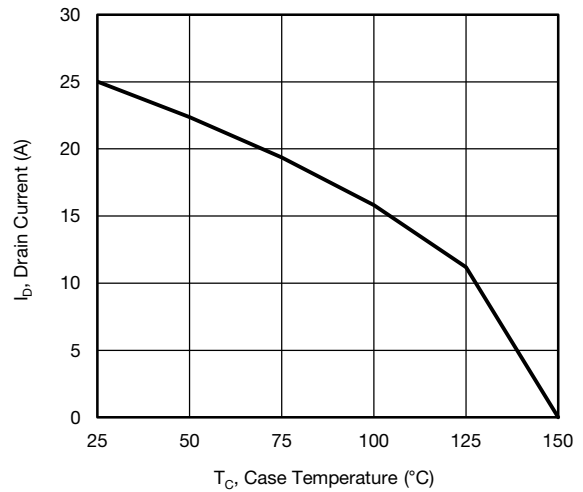


Fig. 9 - Maximum Drain Current vs. Case Temperature

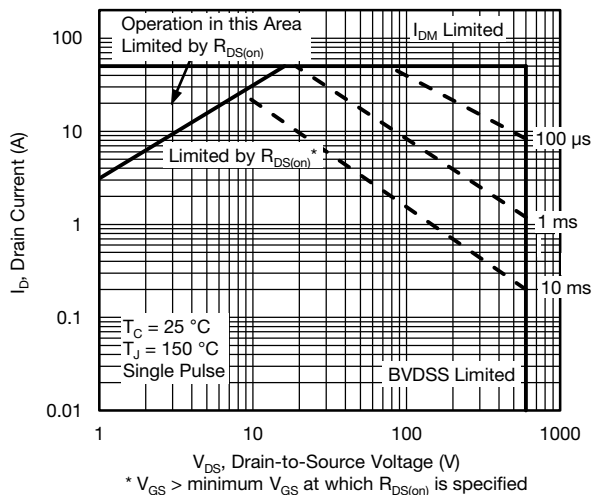


Fig. 8 - Maximum Safe Operating Area

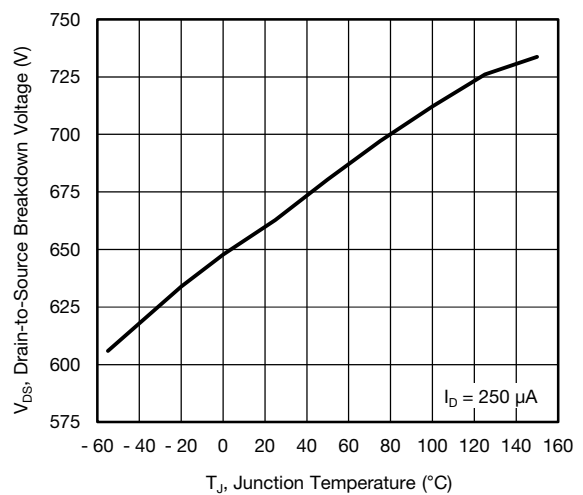


Fig. 10 - Temperature vs. Drain-to-Source Voltage

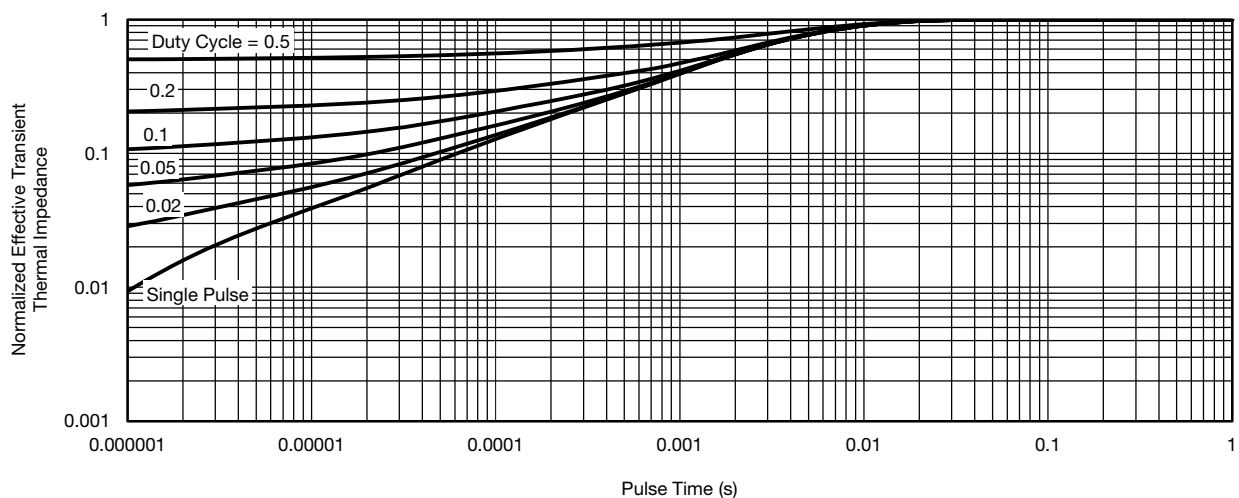


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

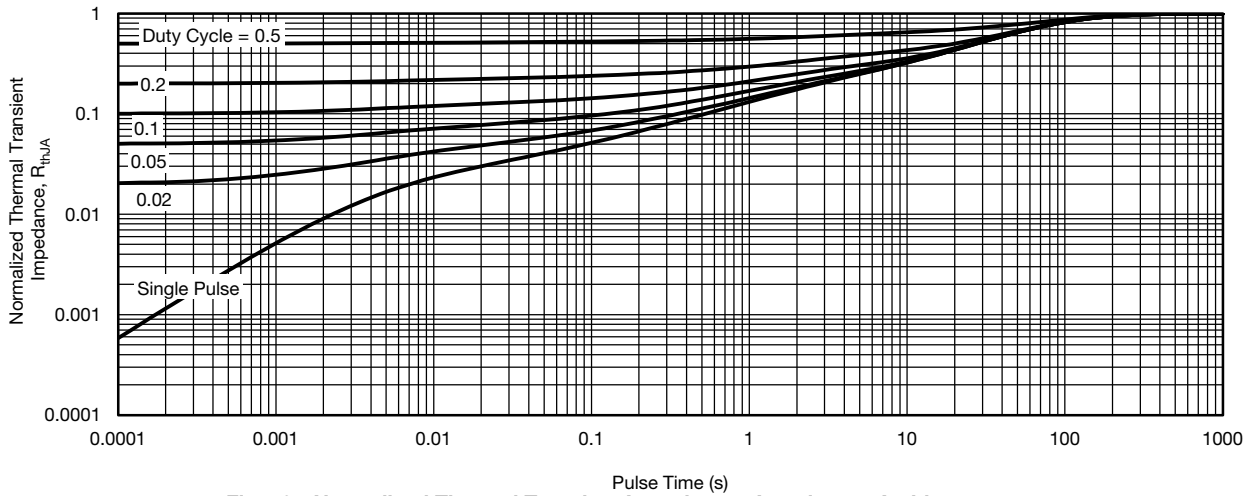


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Ambient

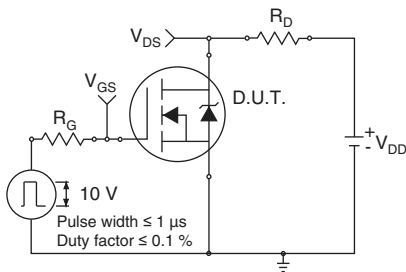


Fig. 13 - Switching Time Test Circuit

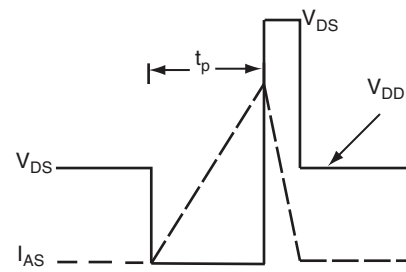


Fig. 16 - Unclamped Inductive Waveforms

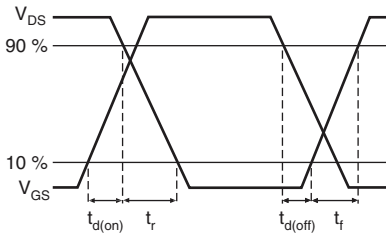


Fig. 14 - Switching Time Waveforms

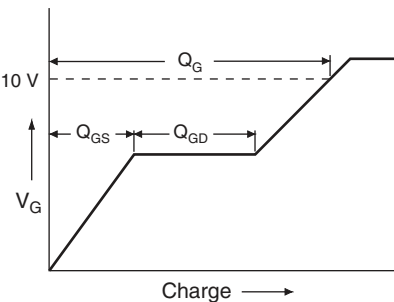


Fig. 17 - Basic Gate Charge Waveform

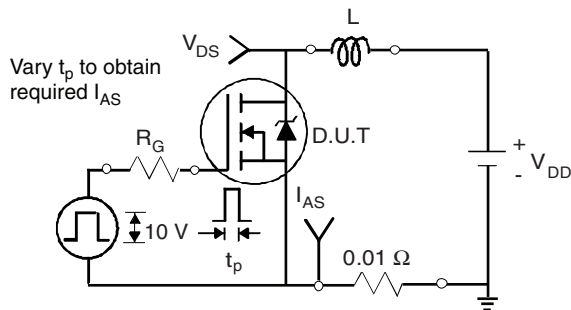


Fig. 15 - Unclamped Inductive Test Circuit

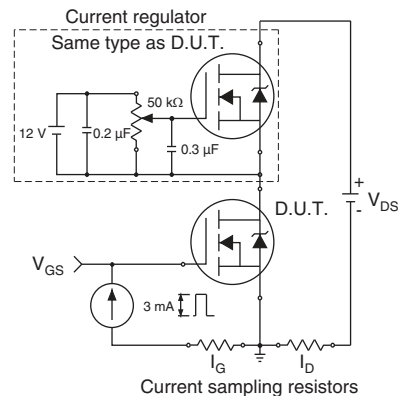
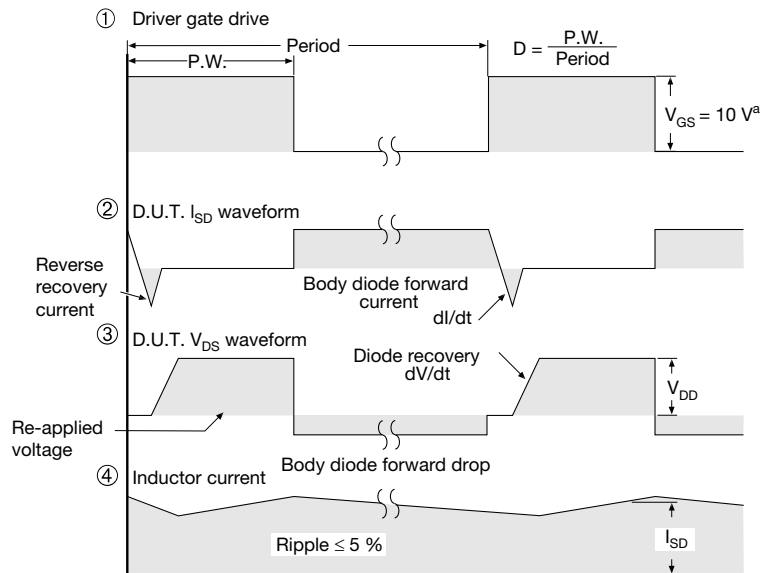
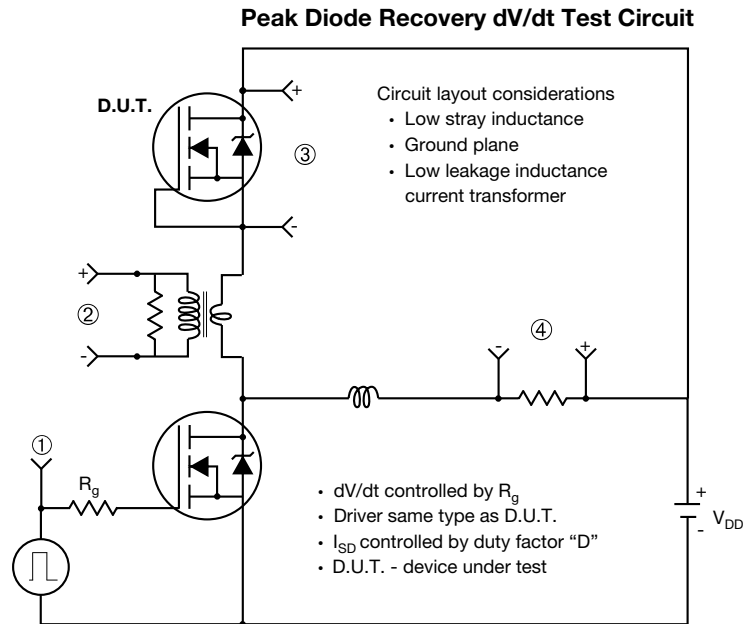


Fig. 18 - Gate Charge Test Circuit



Note

a. $V_{GS} = 5 V$ for logic level devices

Fig. 19 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91578.

PowerPAK® 8 x 8 Case Outline



DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A ⁸	0.95	1.00	1.05	0.037	0.039	0.041
A1	0.00	-	0.05	0.000	-	0.002
A2	020 ref.			0.008 ref.		
b ⁴	0.95	1.00	1.05	0.037	0.039	0.041
D	7.90	8.00	8.10	0.311	0.315	0.319
D2	7.10	7.20	7.30	0.280	0.283	0.287
D3	0.40 BSC			0.016 BSC		
e	2.00 BSC			0.079 BSC		
E	7.90	8.00	8.10	0.311	0.315	0.319
E2	4.30	4.35	4.40	0.169	0.171	0.173
E3	0.40 BSC			0.016 BSC		
K	2.75 BSC			0.108 BSC		
L	0.45	0.50	0.55	0.018	0.020	0.022
N ³	8			8		

Notes

1. Use millimeters as the primary measurement.
2. Dimensioning and tolerances conform to ASME Y14.5 M - 1994.
3. N is the number of terminals.
4. Package warpage max. 0.08 mm.
5. The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body.
6. Exact shape and size of this feature is optional.

ECN: T15-0225-Rev. A, 18-May-15
 DWG: 6041



Recommended Minimum PADs for PowerPAK® 8 mm x 8 mm



Dimensions in millimeters



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